



Product Change Notification

110800 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

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Product Change Notification

Change Notification #: 110800 - 01
Change Title: Intel® CABLE DOCSIS PRODUCTS
DNCE2500, DNCE2500G, DNCE2500GU,
DNCE2510, DNCE2510GU, DNCE2530,
DNCE2530G, DNCE2530GU, DNCE2540,
PCN 110800-01, Product Material, Label,
Reason for Revision: Adding Packing
Material Information
Date of Publication: July 28, 2011

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Oct 3, 2011
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Description of Change to the Customer:

Reason for Revision: Adding Packing Material Information

In addition to the changes listed below and in order to move to standard Intel packing methodology, all packing materials will change to align with the Intel standards for this package type and location with the exception of the tray which will not change. The new packing is functionally equivalent with the existing methods and materials.

In line with the acquisition of the cable modem division of Texas Instruments in November 2010, Intel is transferring the products listed in the products affected table from the existing TI supply chain to an Intel managed supply chain. This consolidation will enable Intel to provide better support to customers in the dynamic market environment.

This will be reflected by a change to the product marking (previously communicated in PCN110535) and the label/shipping documents, which will show the country of origin being China (See image below). The change to the product marking (for Puma 5 only) will not be implemented on production from the TI supply chain, but will be implemented on all production from the new supply chain in order to give added traceability of the change. Production of Puma 3 and 4 will have the marking change implemented as previously announced.

We will be moving the assembly/test location from the existing TI facility to an Intel managed subcontractor in China. As part of this

transition we are changing the assembly material set to align with the Intel standard for this package type and location. The Intel standard material set is already qualified and in High Volume Manufacturing (HVM). In addition we will be conducting a qualification of the material set with Puma 5. The specific changes will include mold compound, die attach material, and copper wire with a thin palladium coating.

The above label is a representation for example purposes only. Actual label will reflect correct product data.

Customer Impact of Change and Recommended Action:

There is no change to the wafer/die, or to the substrate design or source. There will be no change to the package dimensions, or in the electrical or reliability performance of the device, and the change is equivalent in terms of form, fit and function.

Customers may receive product from either supply chain until existing inventory is depleted. There will be no change to the product order code.

Products Affected / Intel Ordering Codes:

Puma #	Base Nm	Marketing Name	Level 1	S Spec	Material Id	Corresponding TI Part #
Puma-5	CE2500	DNCE2500	DNCE2500S LHCL	S LHCL	911311	TNETC4800ZDW
		DNCE2500G	DNCE2500GS LHCU	S LHCU	911319	TNETC4800ZDWG
		DNCE2500GU	DNCE2500GUS LHCV	S LHCV	911451	TNETC4800ZDWGU
		DNCE2510	DNCE2510S LHCM	S LHCM	911312	TNETC4810ZDW
		DNCE2510GU	DNCE2510GUS LHCW	S LHCW	911321	TNETC4810ZDWGU
		DNCE2530	DNCE2530S LHCQ	S LHCQ	911315	TNETC4830ZDW
		DNCE2530G	DNCE2530GS LHCY	S LHCY	911323	TNETC4830ZDWG
		DNCE2530GU	DNCE2530GUS LHCZ	S LHCZ	911452	TNETC4830ZDWGU
		DNCE2540	DNCE2540S LHCT	S LHCT	911318	TNETC4840ZDW

Reference Documents / Attachments:

Document:
PCN110535

Location #:

PCN Revision History:

Date of Revision:

July 1, 2011
July 28, 2011

Revision Number:

00
01

Reason:

Originally Published PCN
Adding Packing Material
Information